

FIG. 1



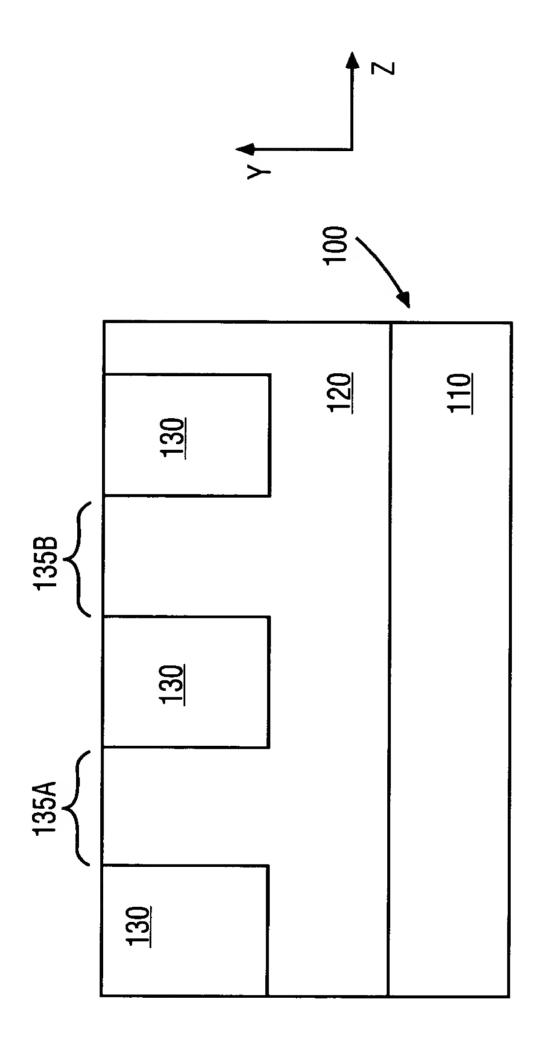


FIG. 2

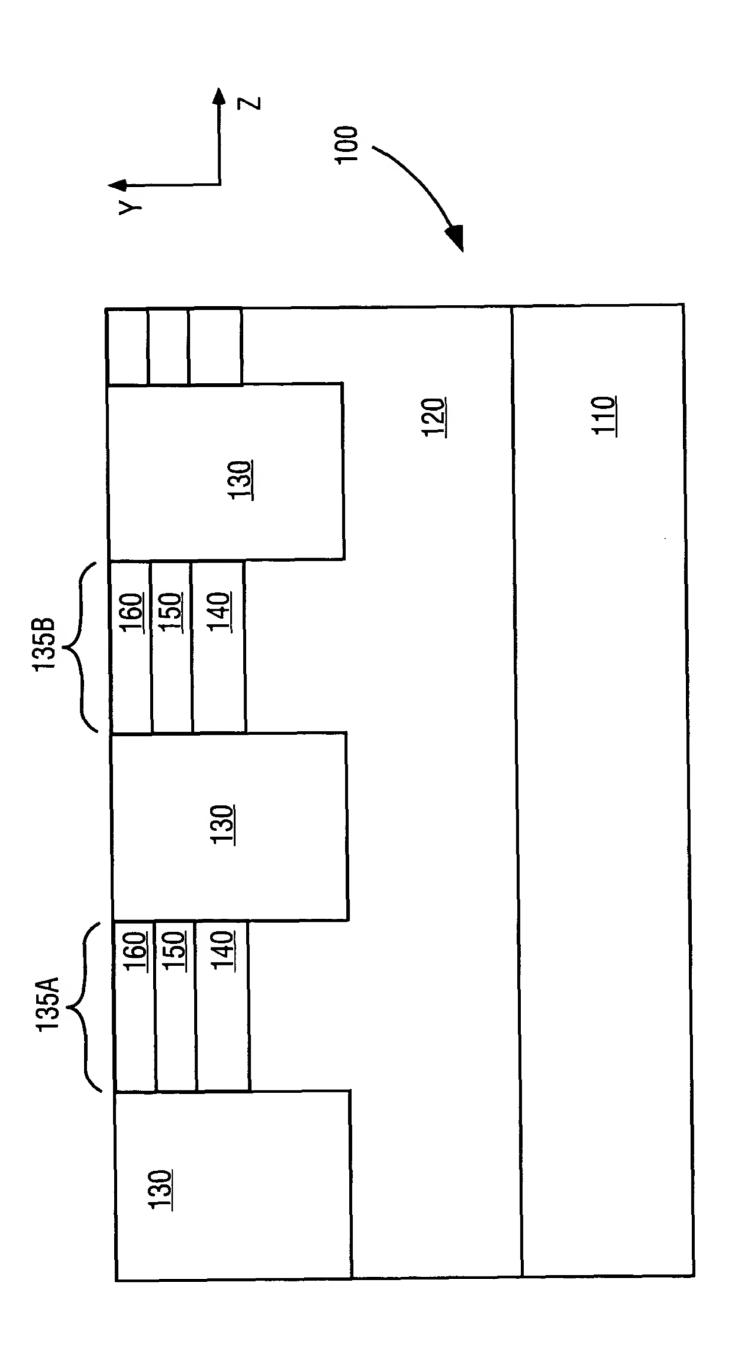


FIG.



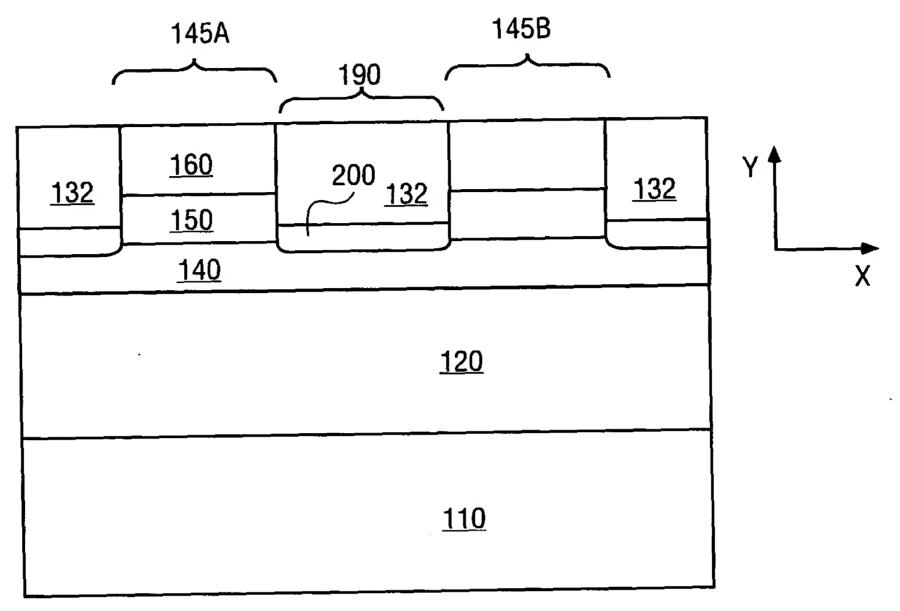


FIG. 4

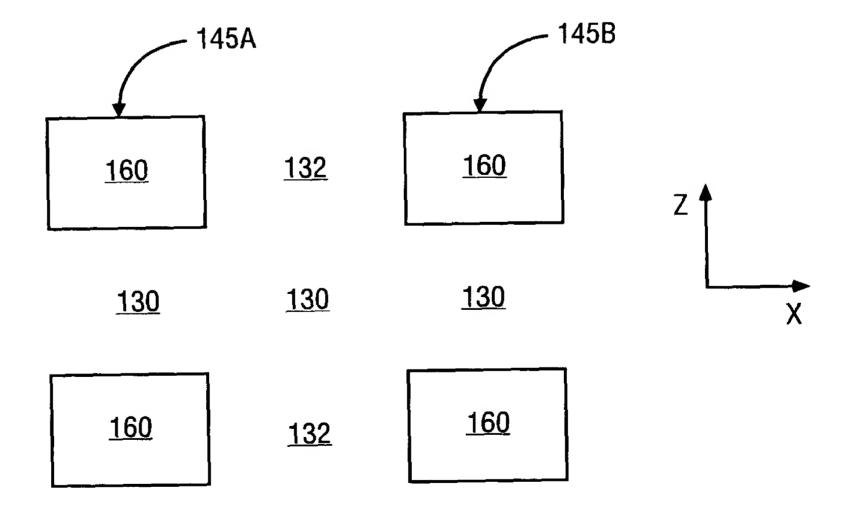
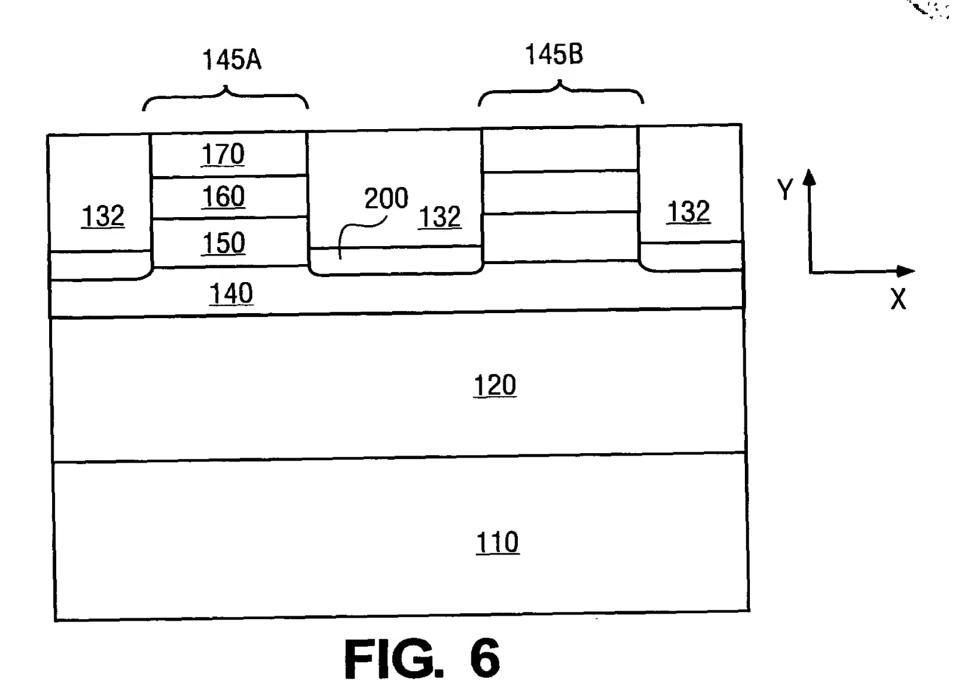


FIG. 5



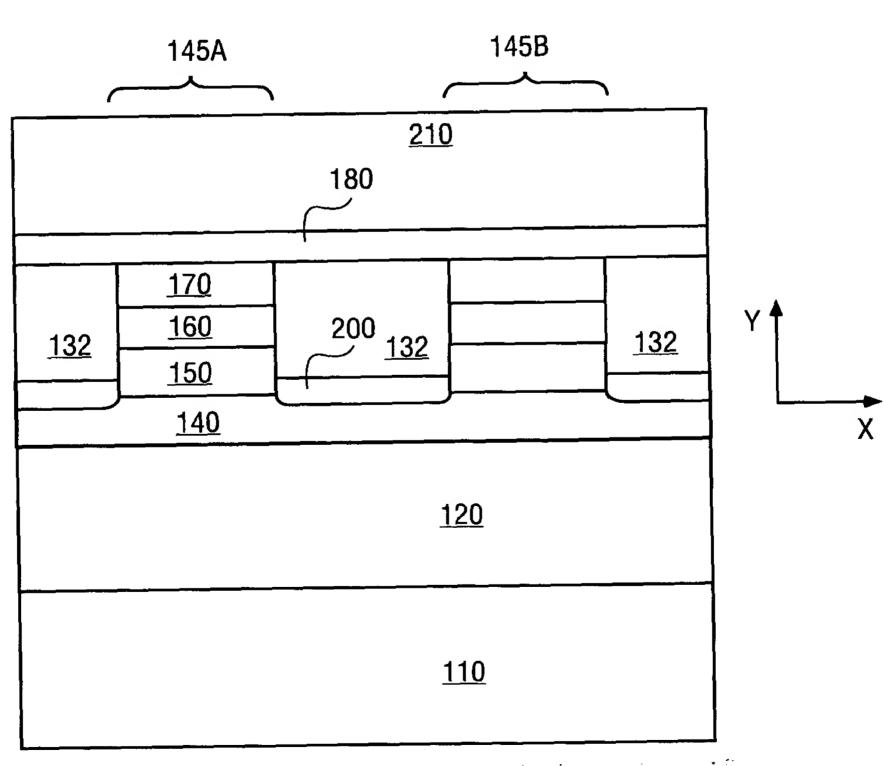


FIG. 7



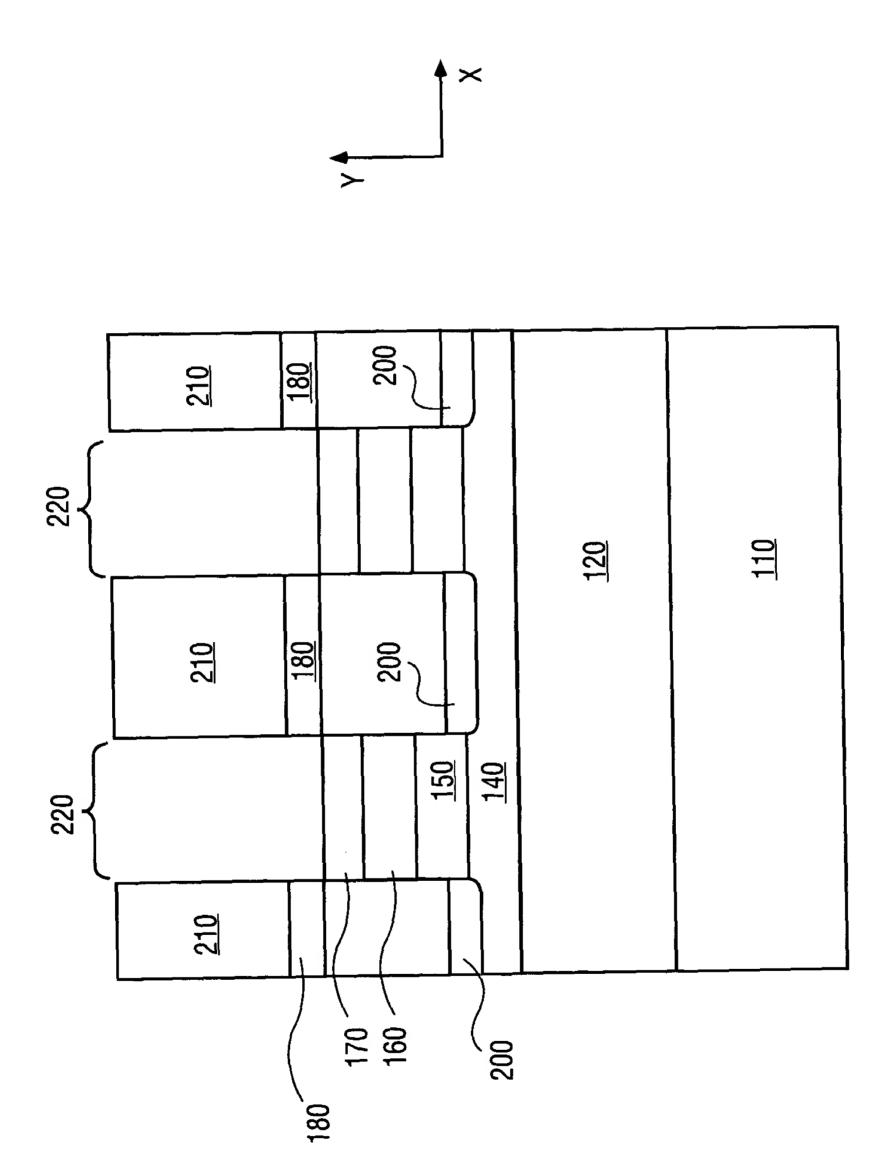
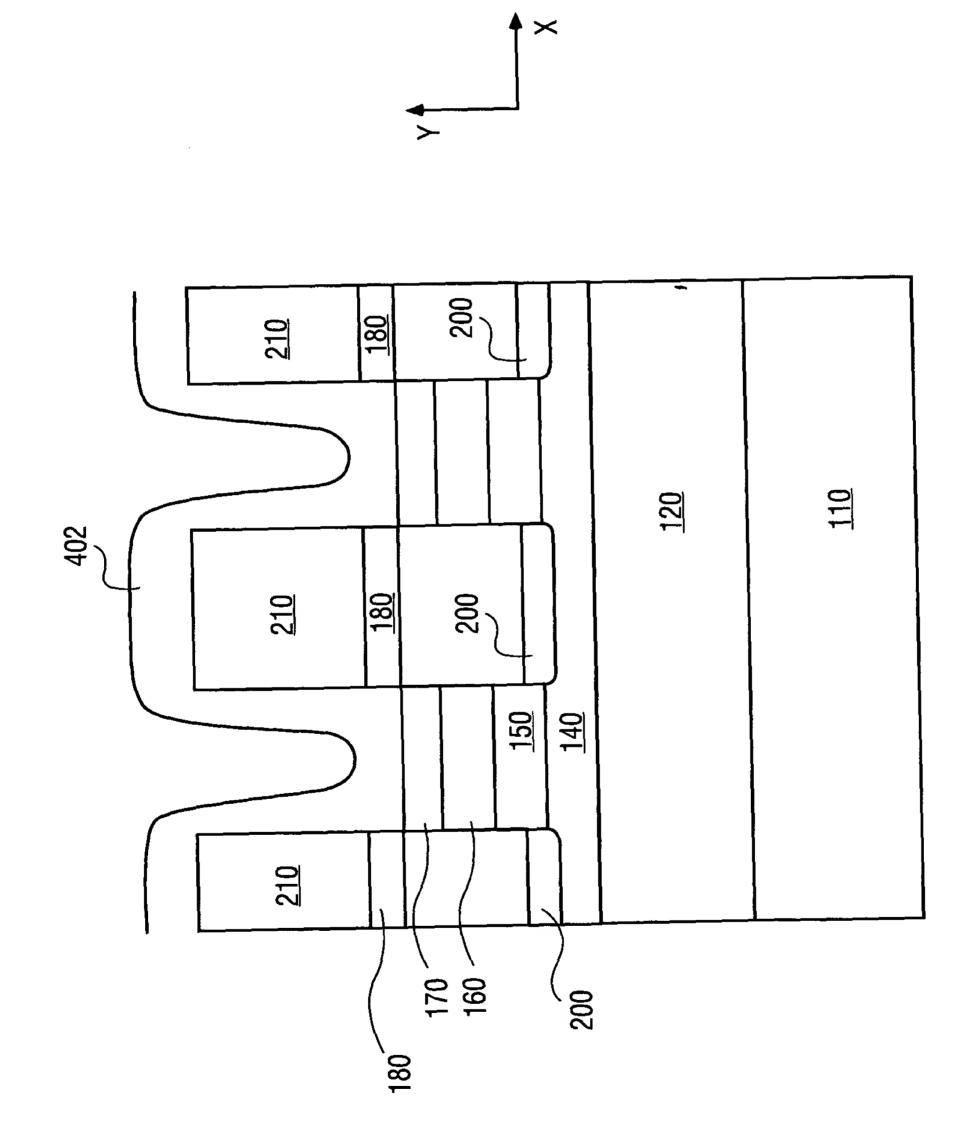


FIG. 8





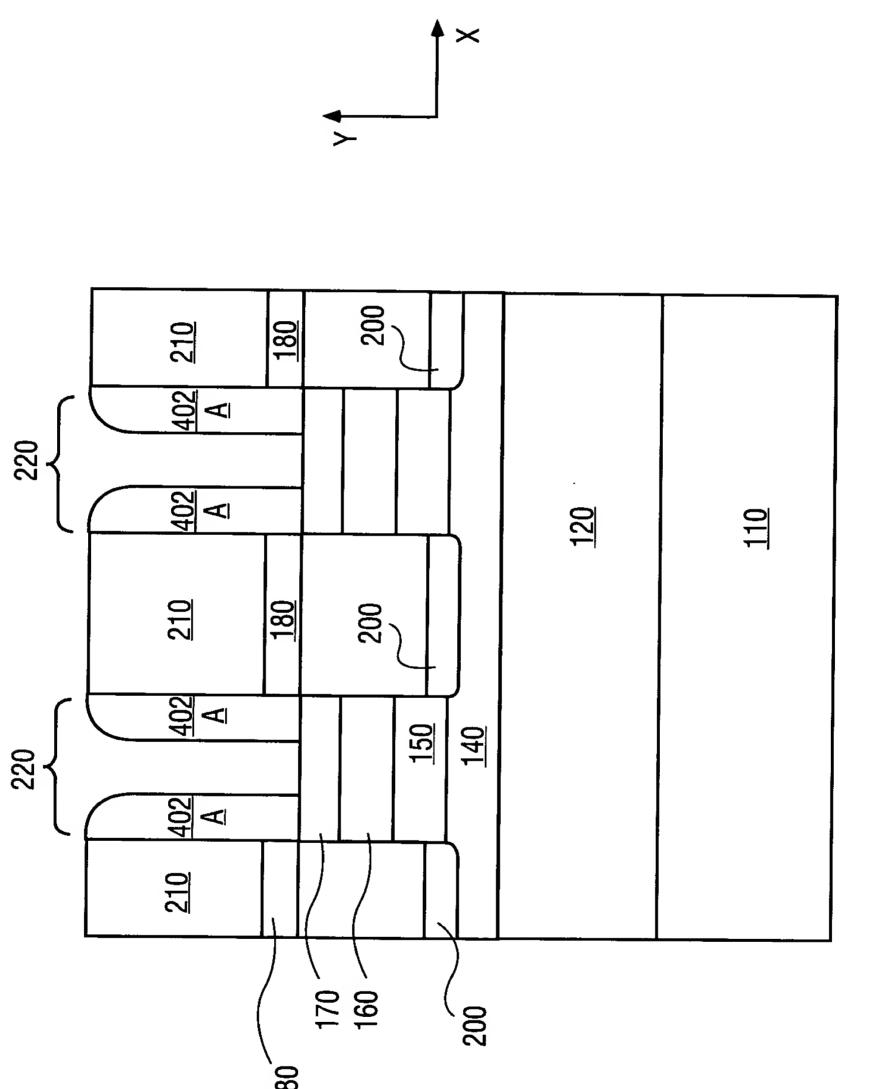
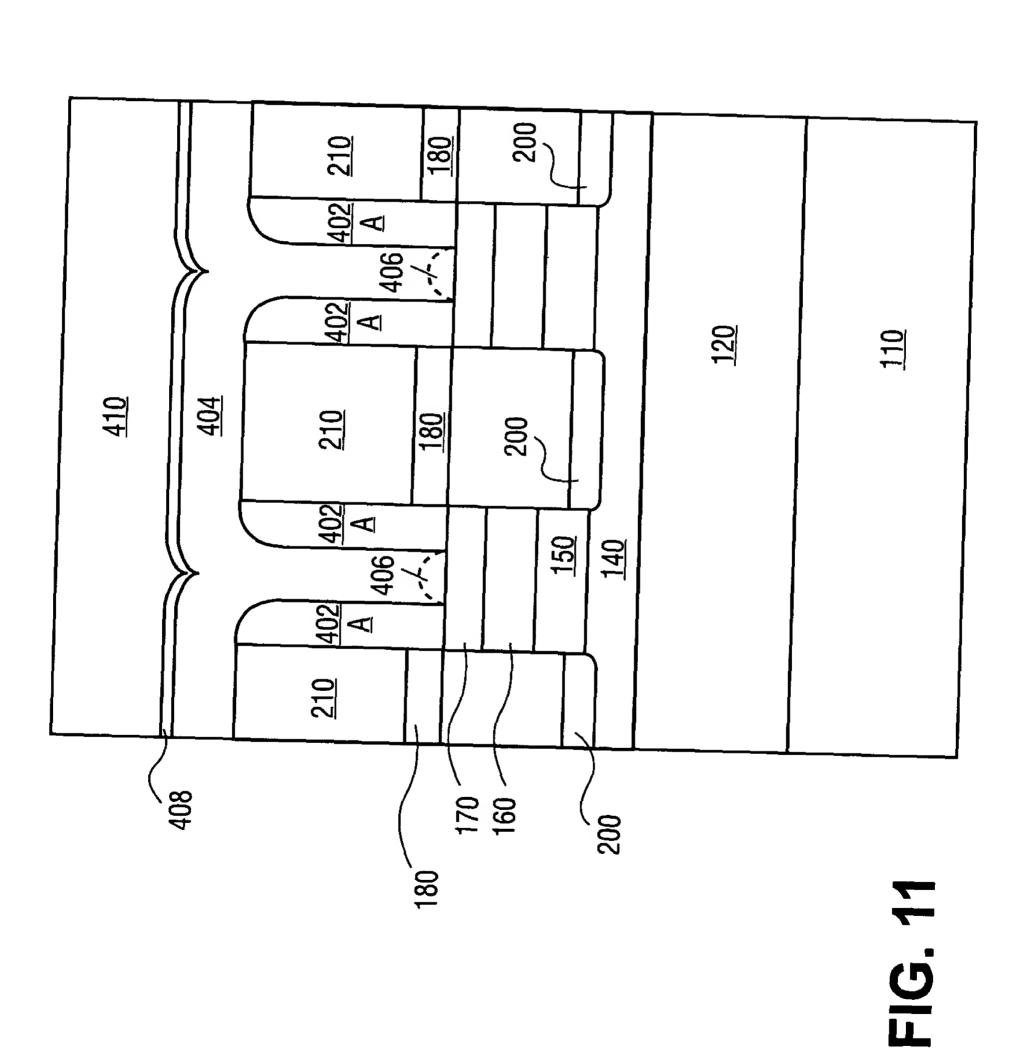
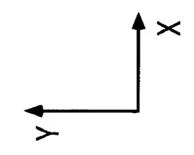


FIG. 10



×





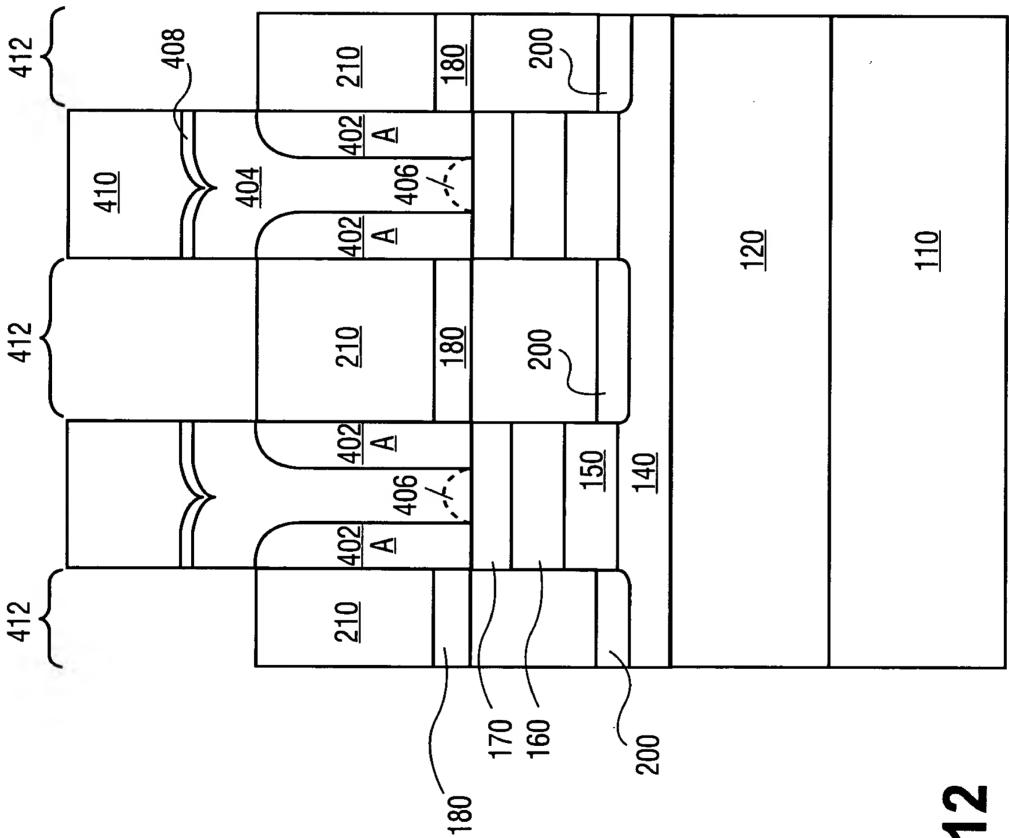
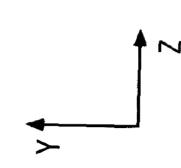


FIG. 12





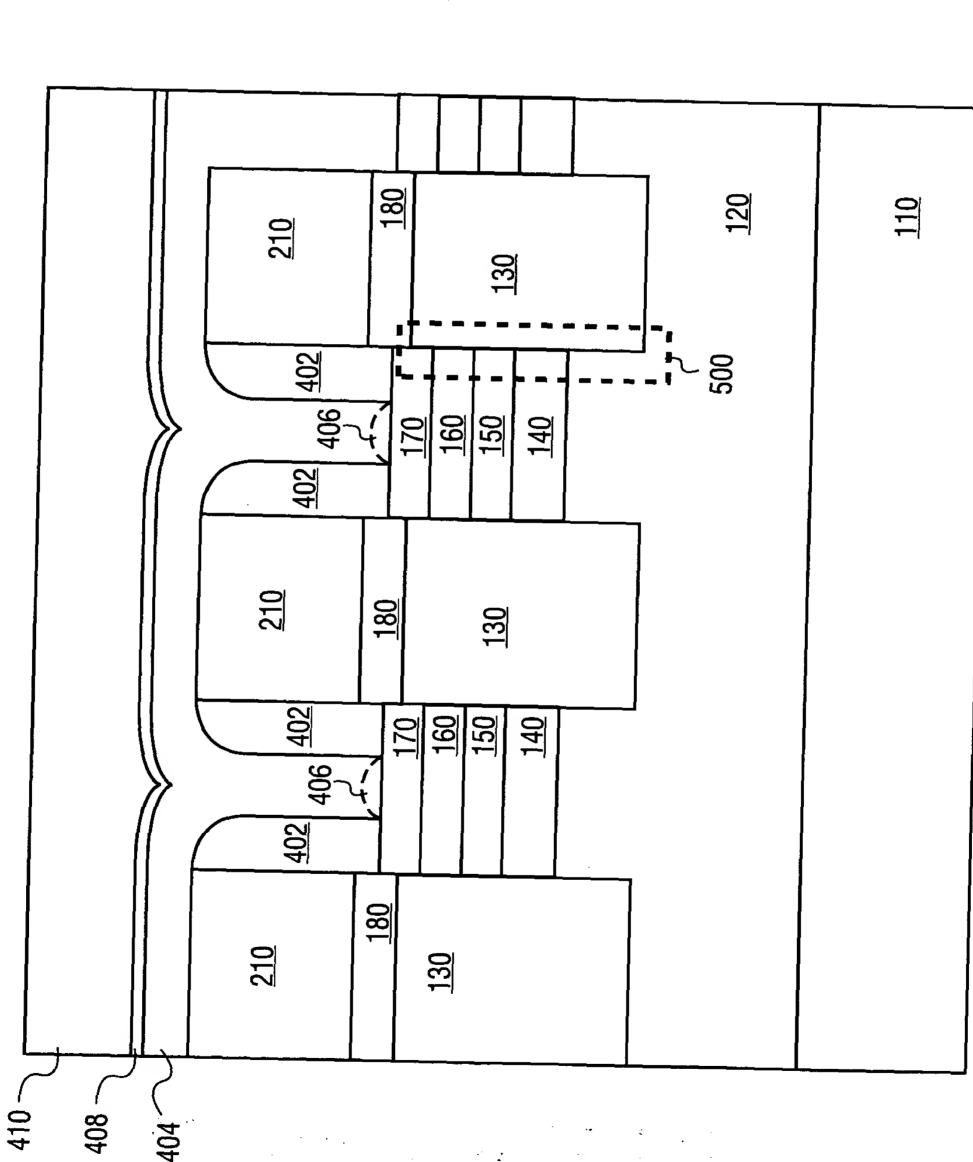
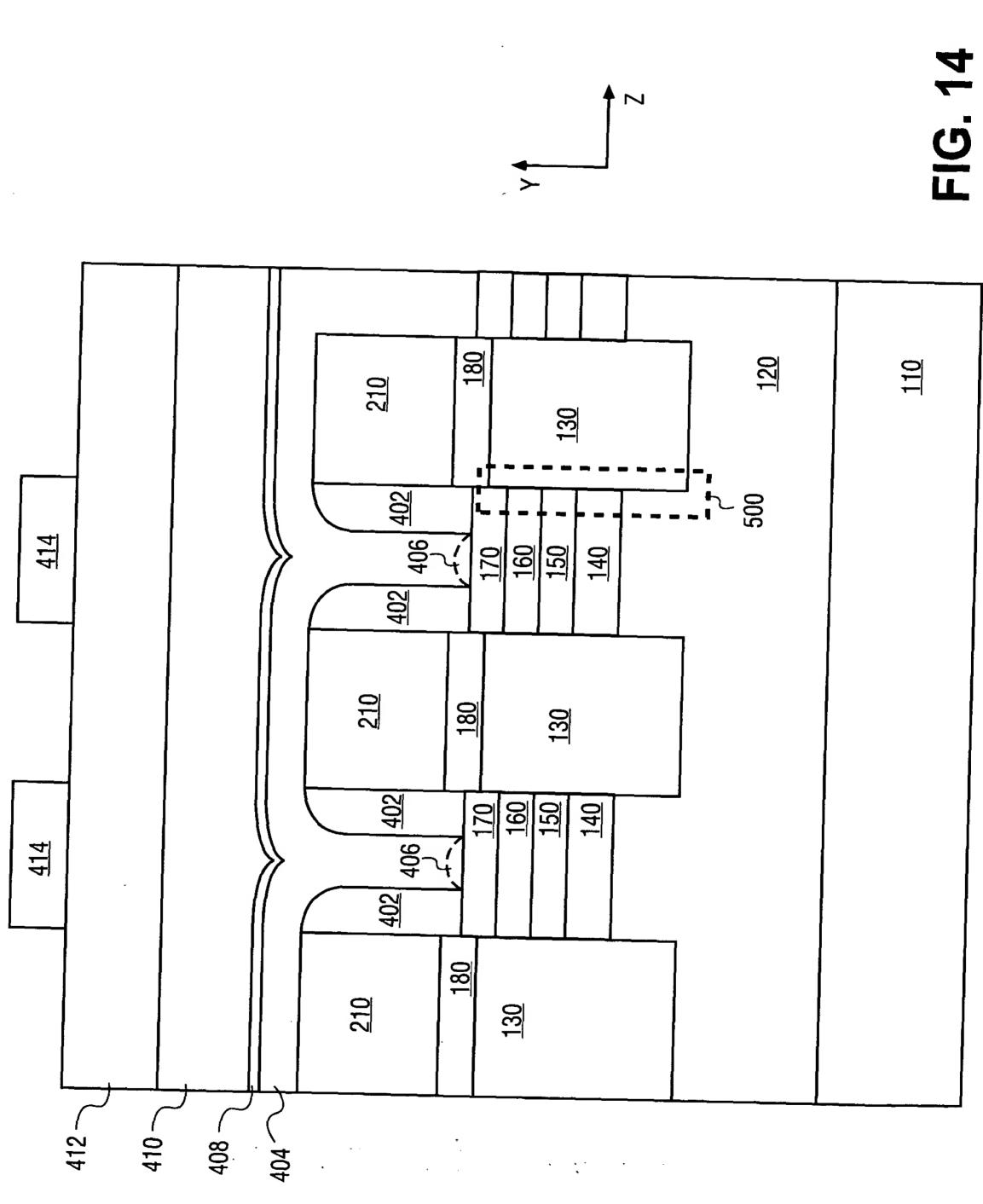


FIG. 13





FORM AN OPENING THROUGH THE DIELECTRIC EXPOSING THE CONTACT.

OPTIONALLY, FORM A SPACER WITHIN THE OPENING AND OPTIONALLY CONFORMALLY FORM THE SPACER ON THE DIELECTRIC AND WITHIN THE OPENING; AND FURTHER OPTIONALLY ANISOTROPICALLY ETCH THE SPACER FROM THE DIELECTRIC USING AN AGENT SELECTIVE FOR THE SPACER.

FORM PROGRAMMABLE MATERIAL WITHIN THE OPENING, THE PROGRAMMABLE MATERIAL ON THE CONTACT.

FORM A CONDUCTOR TO THE PROGRAMMABLE MATERIAL.

OPTIONALLY, FORM A BARRIER BETWEEN THE PROGRAMMABLE MATERIAL AND THE CONDUCTOR.

OPTIONALLY, FORM AN ISOLATION DEVICE BETWEEN THE CONTACT AND A SIGNAL LINE.

FORM A DIELECTRIC ON THE CONDUCTOR.

FORM A VIA IN THE DIELECTRIC TO THE CONTACT. FILL THE VIA WITH CONDUCTIVE MATERIAL.

FORM A CONDUCTOR ON THE DIELECTRIC.

FIG. 15

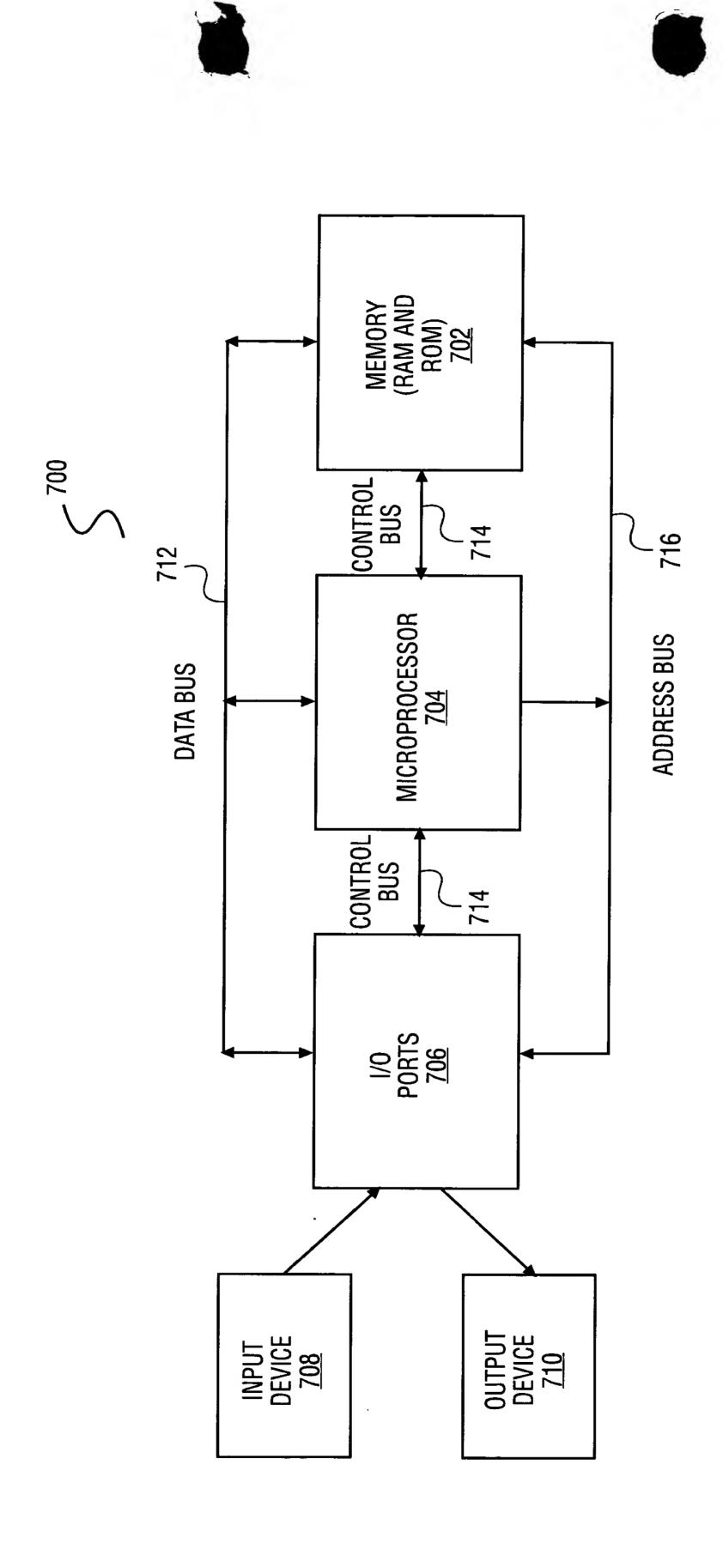


FIG. 16